

1. WR specs (layer 2). This should include a study of reliability/robustness. CERN.
2. Higher layer protocol specs. Discussion on the drivers as well. Cosylab/CERN/GSI.
3. OHR (see <http://ab-dep-co-ht.web.cern.ch/ab-dep-co-ht/documents/2008/Hardware/OHRFuncSpec.pdf>). Cosylab.
4. VHDL/Verilog choice and guidelines.CERN/AAS/IN2P3.
5. PCB design standards. Choice of a standard tool? Oregano/CERN.
6. Do a master.CERN/GSI.
7. Do a switch. CERN/(IN2P3 if uTCA).
8. Do a slave. IN2P3/AAS.
9. Extensive integration testing.
10. Planning and management.AAS/CERN.
11. System Requirements including architecture specification. Cosylab/CERN.
12. FP7 paperwork. CERN.
13. Network simulation. AAS.